



Comet: Positioned at the Heart of Semiconductor Growth

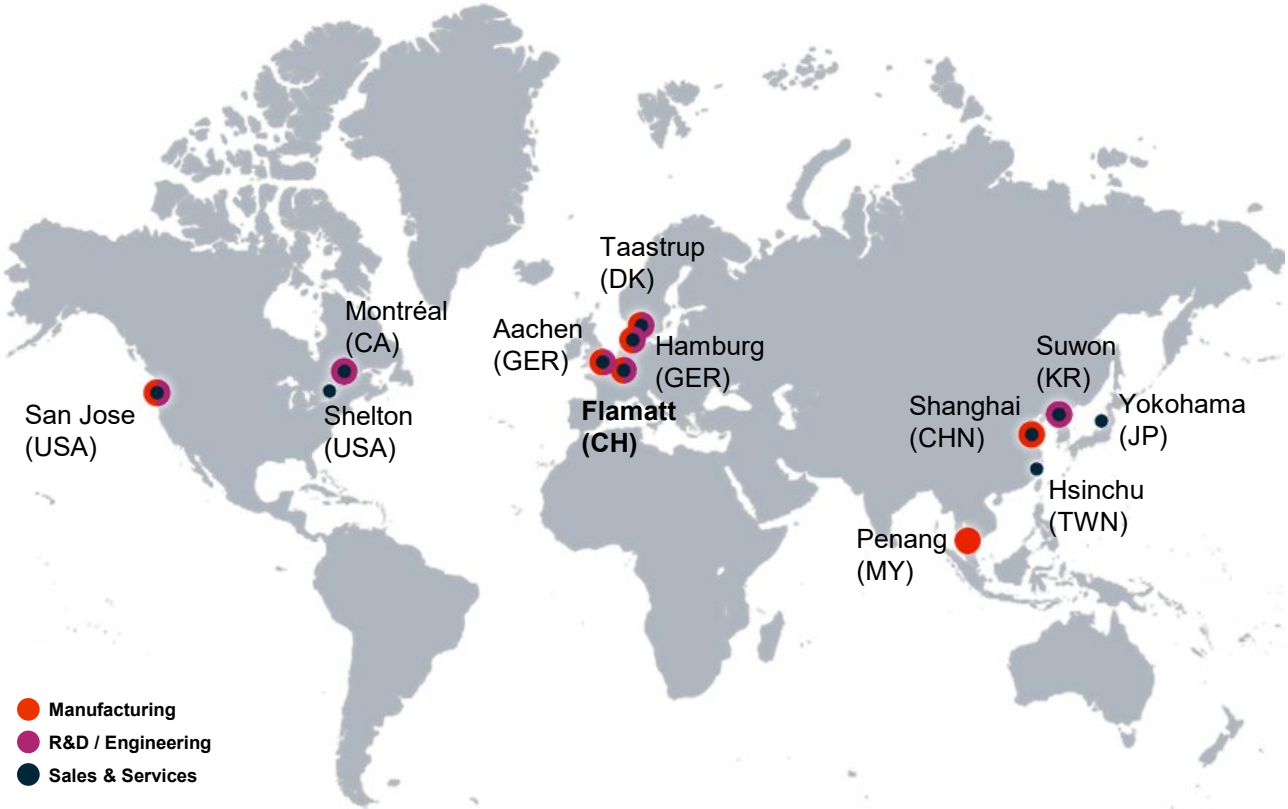
Octavian Seminar 2026
Davos / January 15, 2026

Christian Witt, CFO

Cautionary Statement Regarding Forward Looking Statements

This document contains forward-looking statements about the Comet Group that may be subject to uncertainty and risk. Readers should therefore be aware that such statements may deviate from actual future outcomes or events. Forward-looking statements in this document are projections of possible future developments. All forward-looking statements are made on the basis of data available to Comet at the time of preparation of this document. The Comet Group assumes no obligation whatsoever to update or revise forward-looking statements in this document, whether as a result of new information, future events or otherwise.

A Global Player with Roots in Switzerland ...



Full-year 2024

<p>1800+ employees</p>	<p>12 Locations</p>	<p>Headquarters in Flamatt, Switzerland</p>
<p>Net sales: CHF 445.4 mn</p>	<p>Distribution</p> <p>62% Asia 20% North America 16% Europe 2% Rest of World</p>	
<p>CHF ~2.2 bn Market cap <i>Jan 6 2026</i></p>	<p>100% Free Float</p>	<p>Listed on Swiss Stock Exchange Symbol: COTN</p>

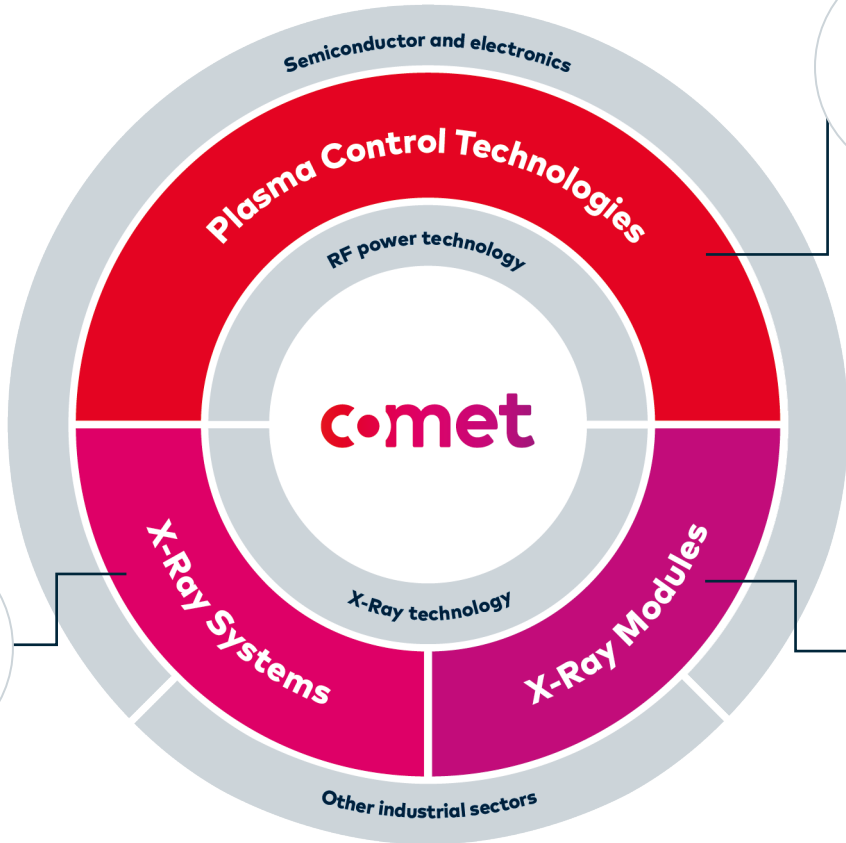
... Committed to Enabling the Semiconductor Industry ...

Top 3
in served markets



High-end x-ray systems for industrial environments from R&D to production

IXS
26%
Group Sales
FY24



PCT
56%
Group Sales
FY24



High-end RF Power delivery systems for plasma applications

#1
in Vaccaps & Matches

IXM
18%
Group Sales
FY24



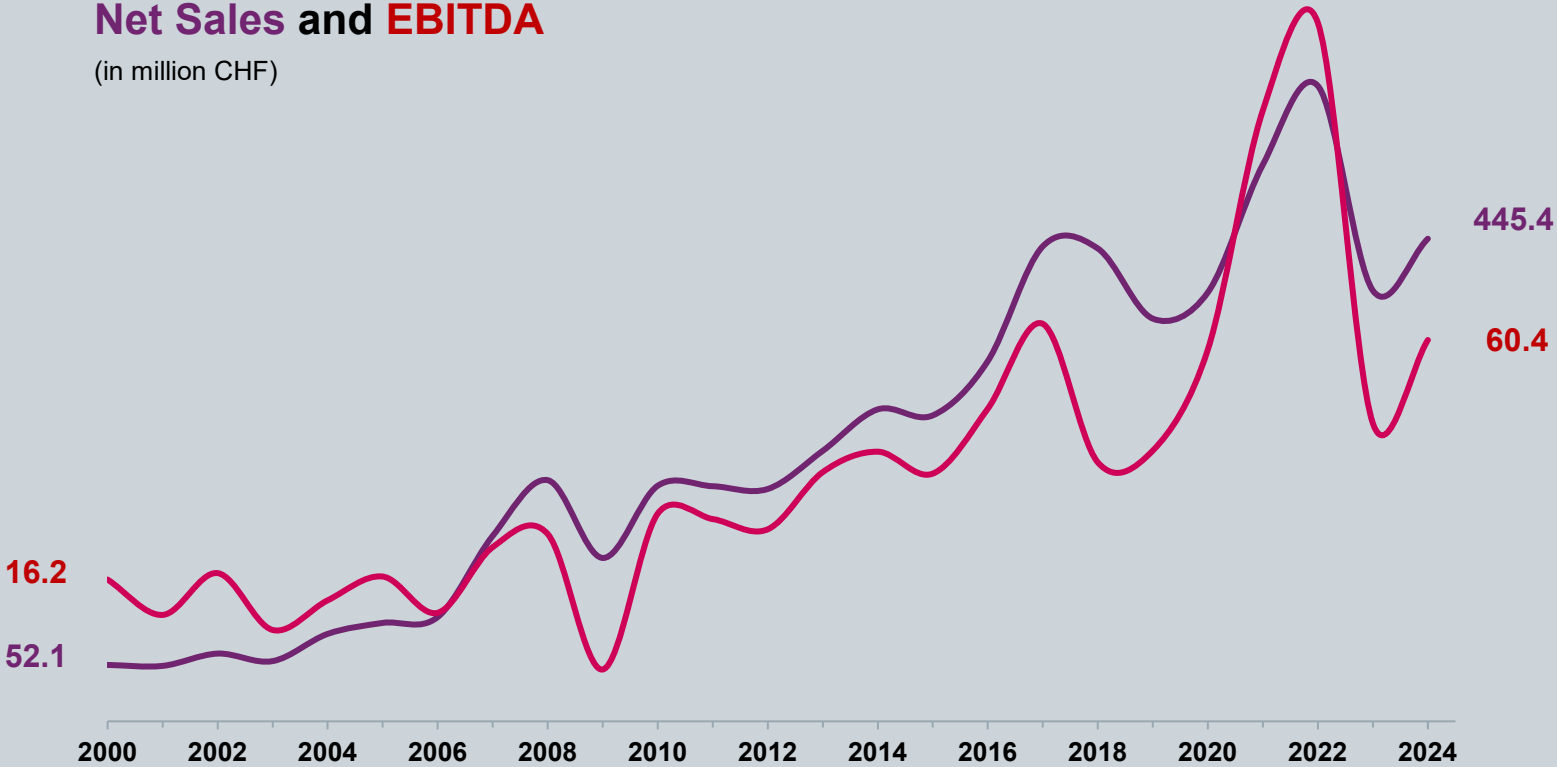
High-end x-ray components and modules for industrial applications

#1
in industrial x-ray sources

... and Creating Long-term Value.

Net Sales and EBITDA

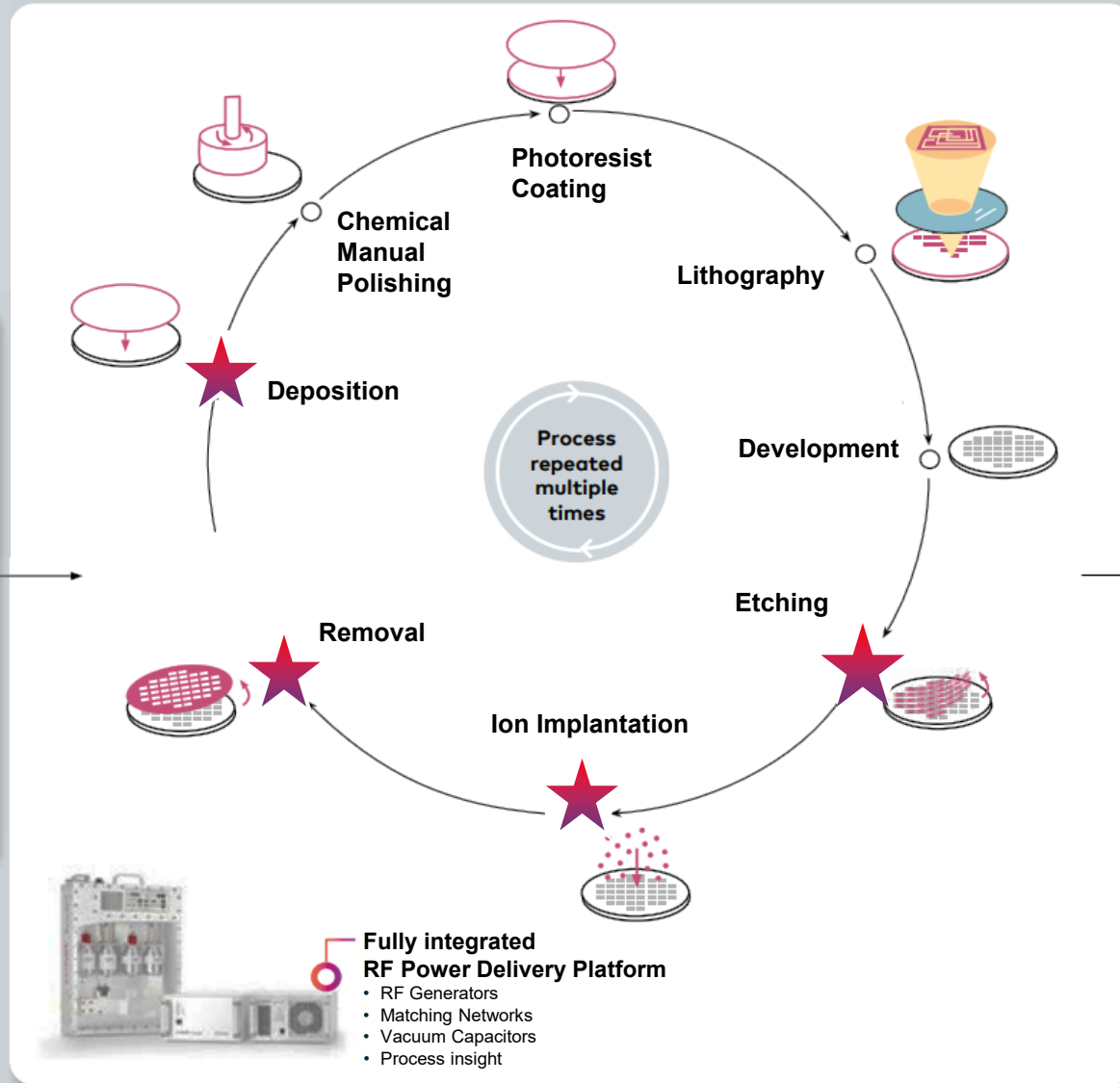
(in million CHF)



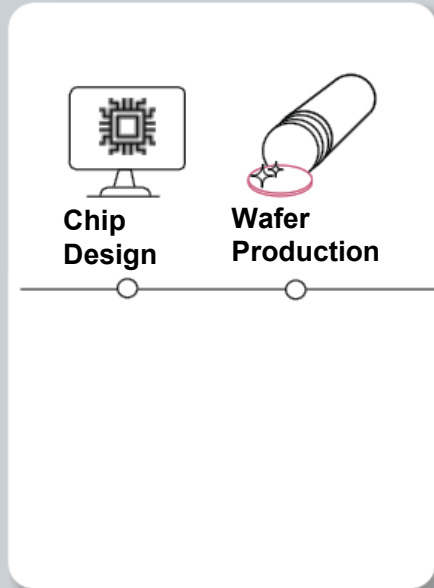
Semiconductors are at the Core of our Strategy and our Growth Opportunity.

Driving Precision and Reliability across Semiconductor Production.

Wafer Fabrication (Front-end Processes)



Design & Raw Material



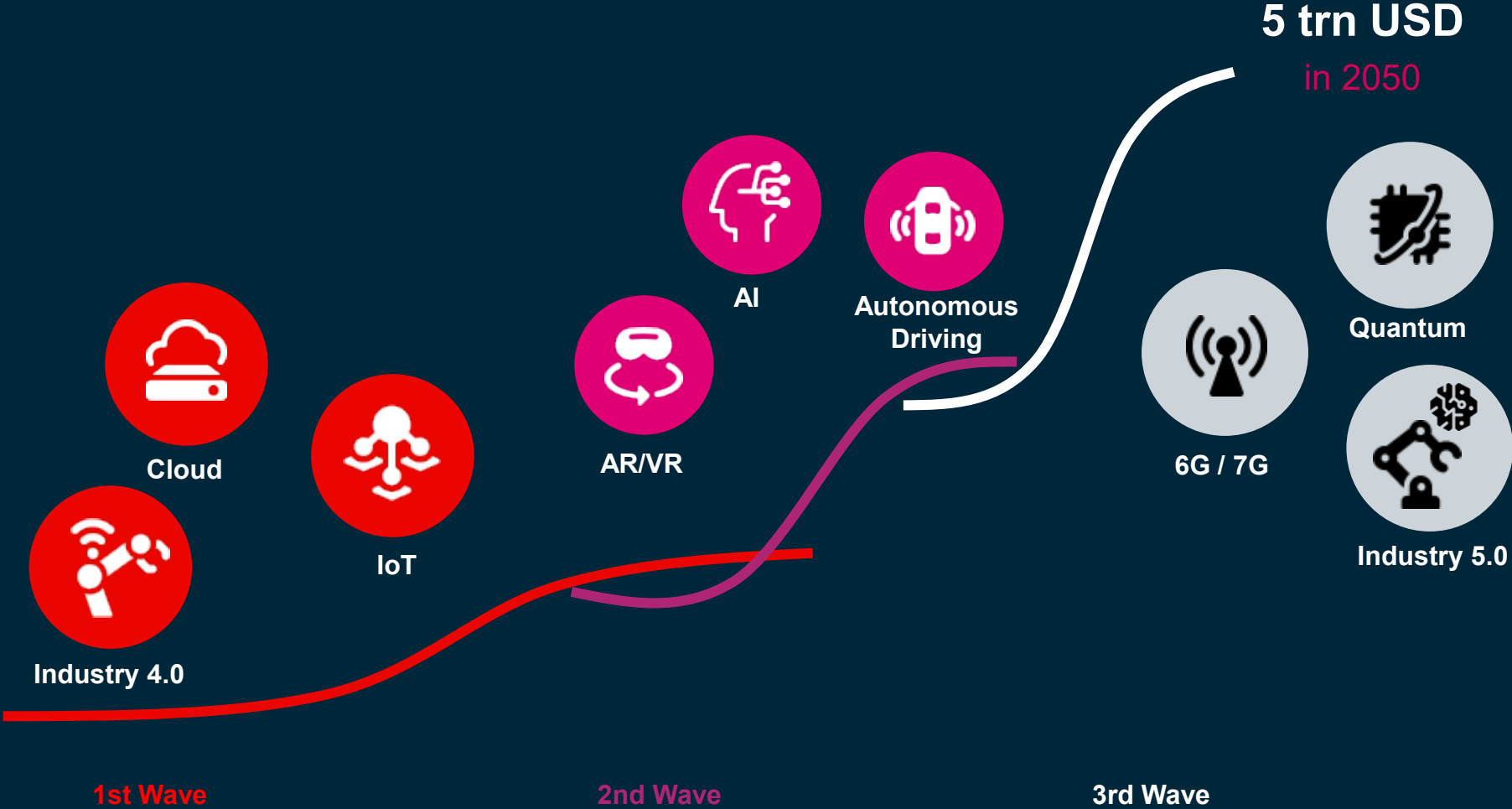
★ Comet solution needed in the process



Assembly & Test (Back-end Processes)



Major Trends Driving the Semiconductor Industry.

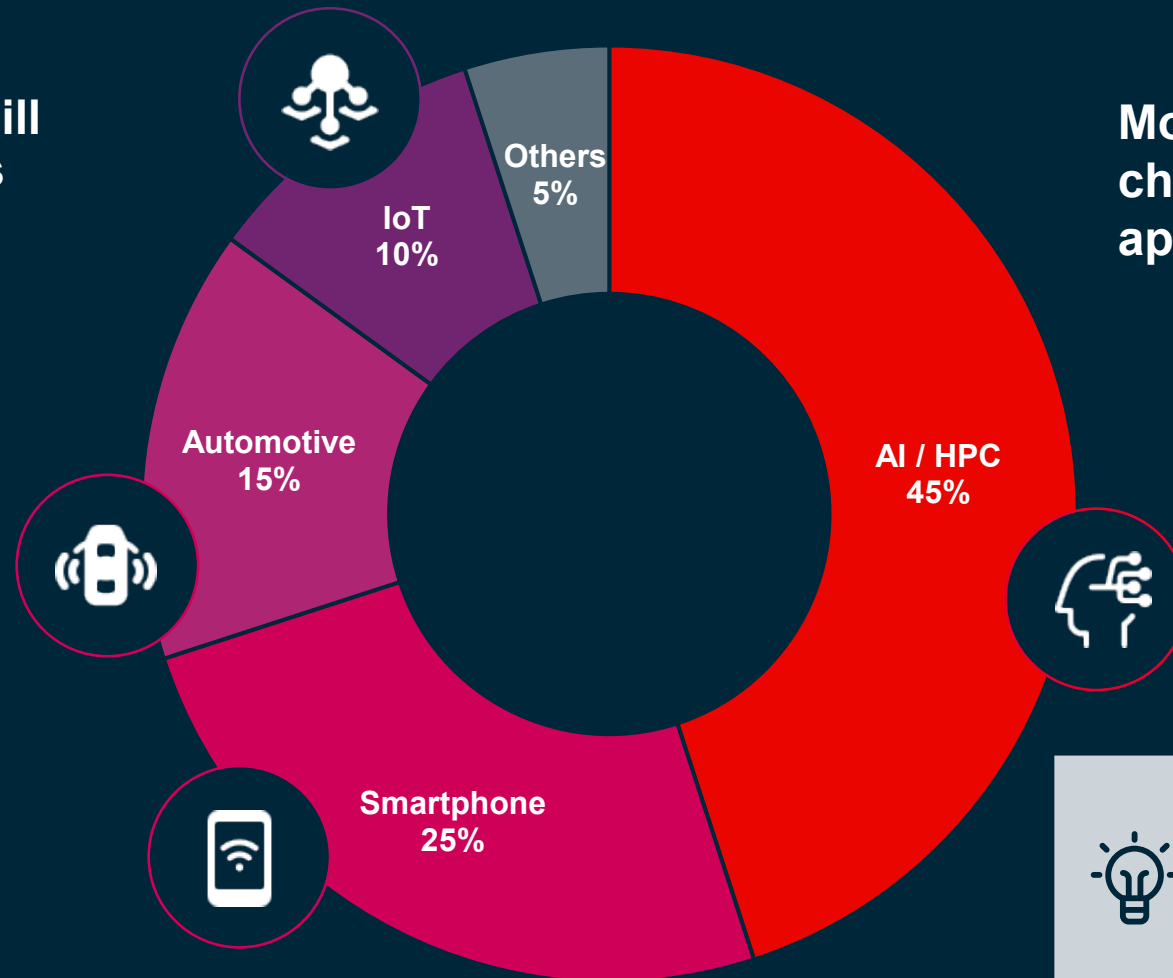


Sources: SEMI 2024 / Tokyo Electron

Mainstream Chips Lead in Volume, High-end Chips Lead in Value.

Most chips by volume will go to consumer markets

Most value will come from chips for AI and HPC applications



2030 semiconductor market by platform > USD 1 trillion



AI / High-Performance Computing demand drives leading-edge utilization
Share increasing to 45% of revenue, consumer chips sustain fab economics.

Sources: [TSMC](#), [Capgemini](#), [IDTechEx](#)

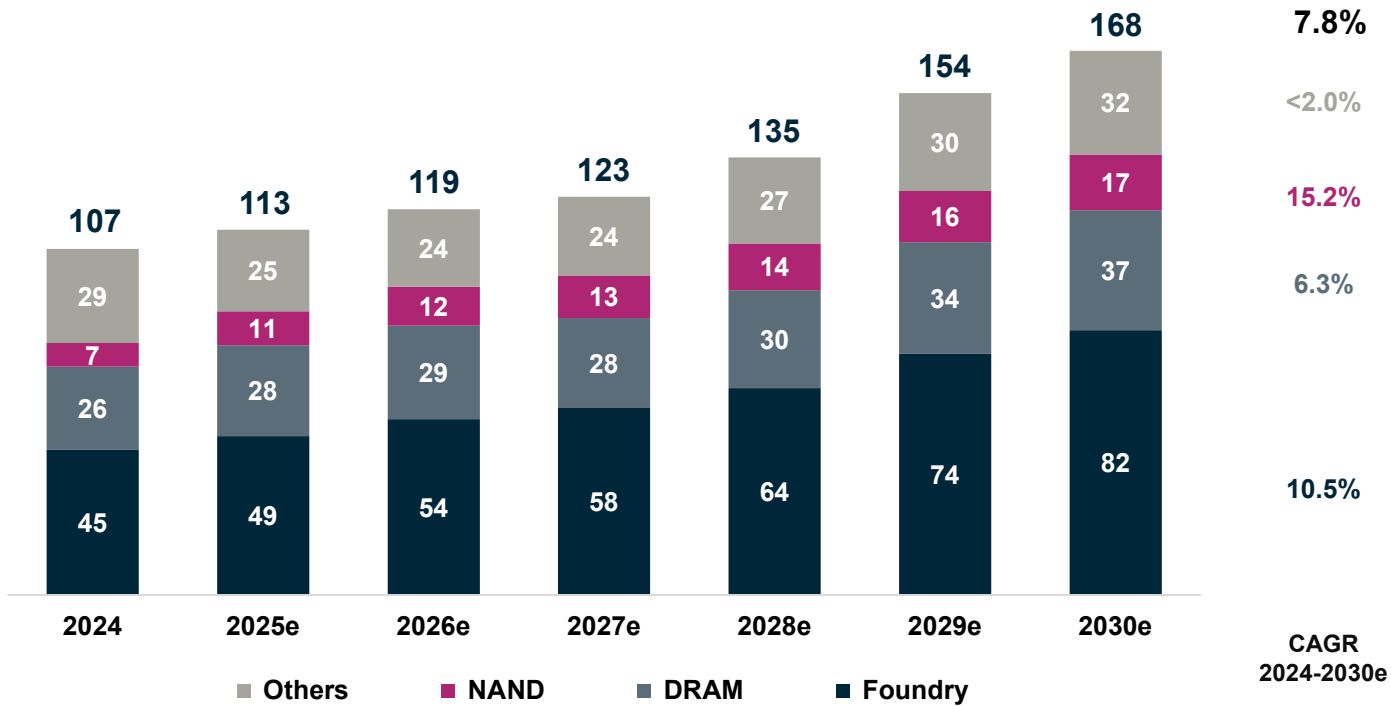
**The Newest AI Applications are the Most Significant
Driver of **Front-end** and **Back-end Innovation.****

AI

Growth Opportunities at Technological Inflection Points in Front-end Process.

WFE revenue by application

(in million USD)



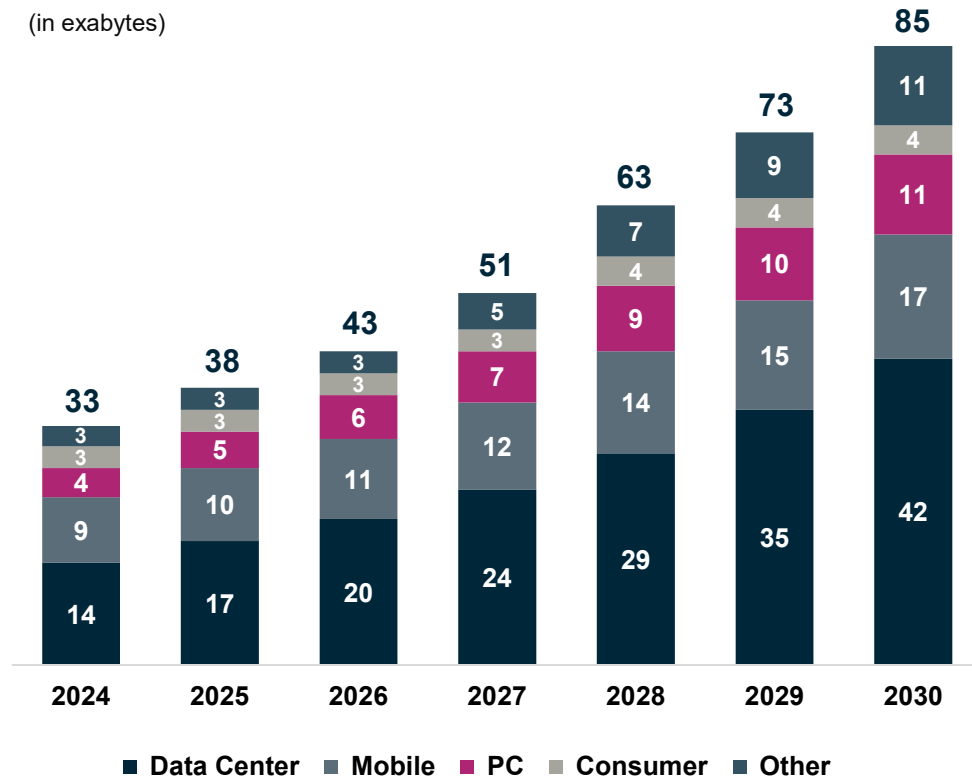
Source: Q3/2025 TechInsights



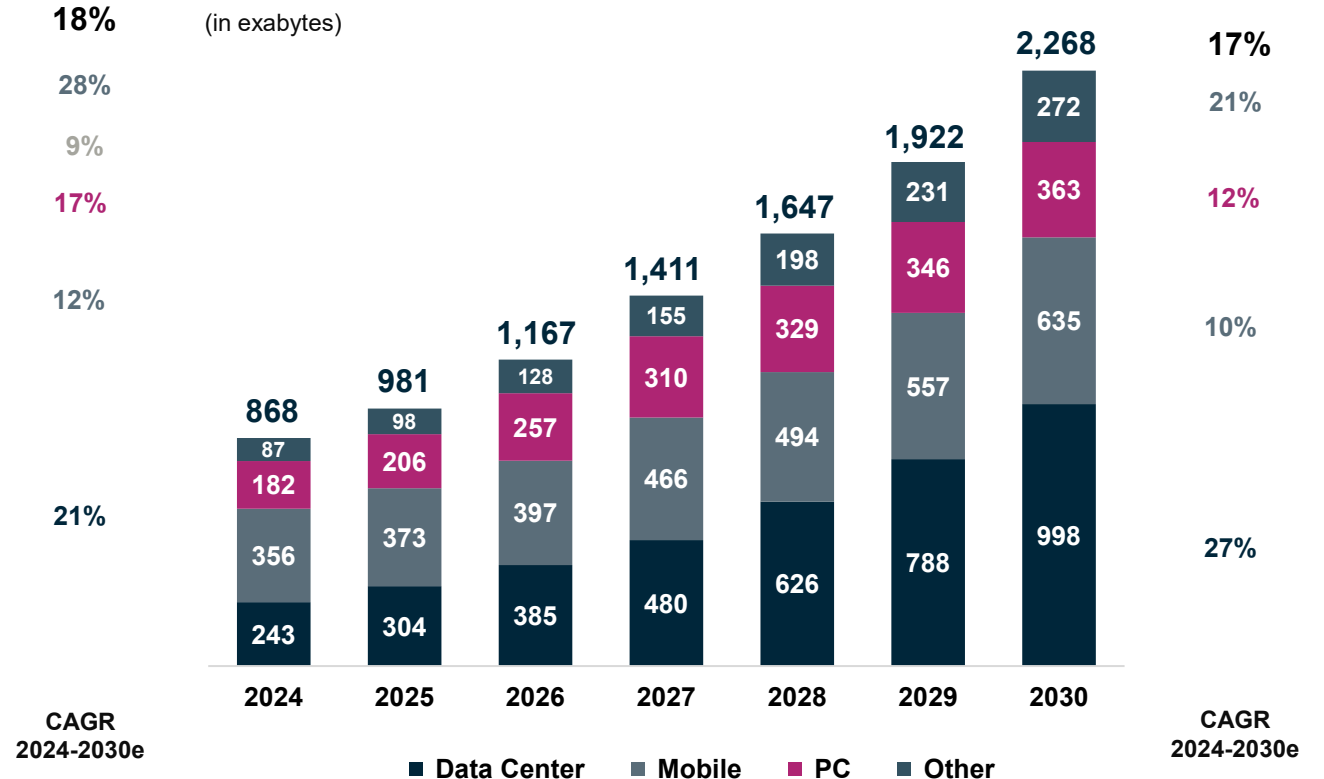
- ▶ **WFE industry drivers for a prolonged growth phase**
 - Structural AI demand
 - Advanced node investments
 - Technology transitions
 - Race for technological sovereignty

Memory Market Outlook: Strong Growth Driven by AI and Data Center Demand.

DRAM demand projections
(in exabytes)



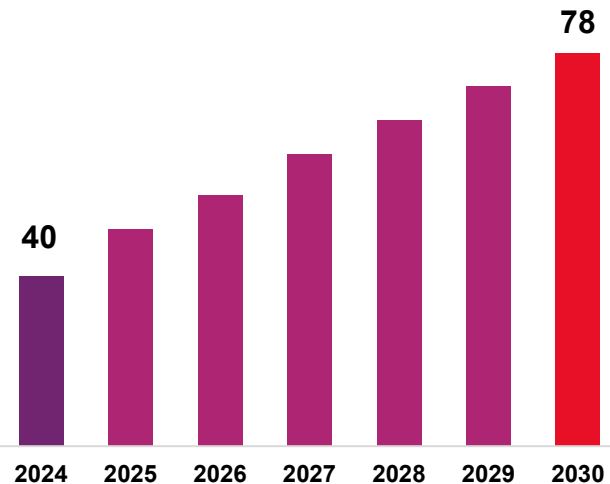
NAND demand projections
(in exabytes)



Source: Yole, DRAM Market Monitor Q3/2025

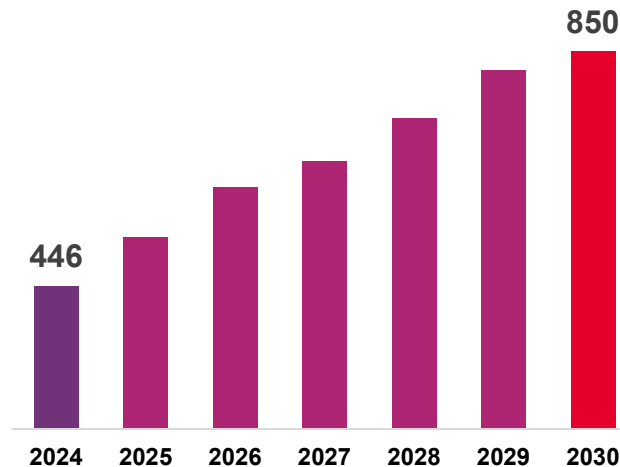
Rising Back-end Demand Unlocks a Major Growth Opportunity.

Advanced Packaging market
(in billion USD)



CAGR 2024 – 2030: 9.5%

Back-end metrology and inspection market
(die level)
(in million USD)



CAGR 2024 – 2030: 11.3%

Source: Yole, Advance Packaging Market Monitor Q3/2025



- ▶ **Inspection/metrology market relevant for Comet is growing 11.3%, faster than Advanced Package (9.5%)**

Main Driver : 2.5D/3D multi-chip packaging

- ▶ **Major applications:** Networks, Data Centers, HPC, High-end smartphones, Automotive
- ▶ **Regionally oriented, consolidated market**
 - 90% of revenue generated in Asia
 - Top 6 suppliers: >80% market share



SAMSUNG



«What» is Pushing the Next Technology Nodes.

WHY

The semiconductor industry advances its progress...

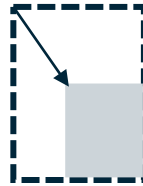
To enable higher performance, efficiency, and more functionality per cost

WHAT

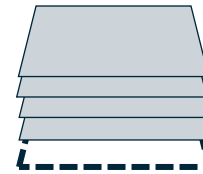
...through continual innovation in chip scaling, architecture, and technology...

Drivers

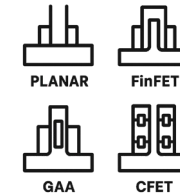
Scaling



Advanced Architectures



Technologies



HOW

...enabled by breakthroughs in new materials, processes, and inspection and testing

Enablers

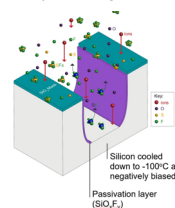
Materials



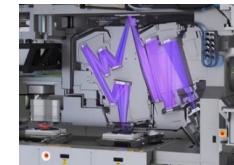
Manufacturing Processes

Examples

Cryo Etching



High NA-EUV



Inspection & Testing

Advanced X-Ray Inspection



Synertia® RFG Market Introduction Progressing well.

Customer Engagement Funnel



Customer Engagement Framework

Comet	Prototype	Released Product	
OEM	OEM Evaluation	OEM Qualification	Semi Fab

Global customer engagements



Customer adoption driven by

- Power accuracy
- Pulse shaping
- Multi-level pulsing (MLP)
- Arc detection and smart data
- Auto-frequency Tuning (AFT)

Engagements across the world with the whole portfolio of frequencies

We are Globally Moving the Needle: X-ray System CA20.

Customer Engagement Funnel

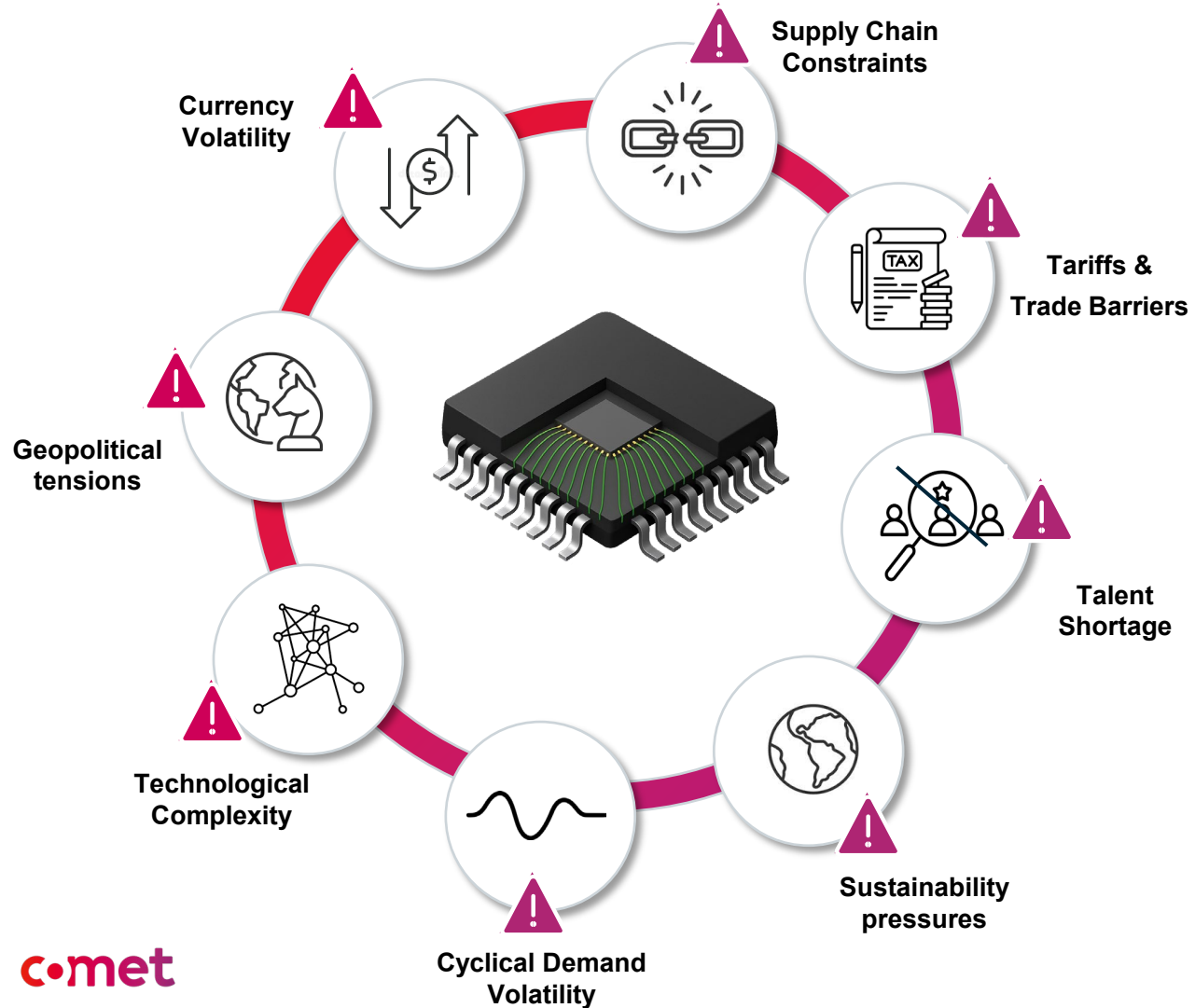


We are moving the needle through



- Strategic Partnerships to have the pulse on the market
- Co-Creation with top market OSAT, IDM, foundry leaders
- Global customer engagements along the complete value chain

Comet in transformation: Adapting to the new reality.



Global shifts demand decisive action

- Industry transformation creates new winners
- Focus to secure leadership in RF Power, x-ray
- Accelerating our transformation to capture opportunities
- Comet: a relevant force in semiconductors

Growth, Efficiency, Resilience: The Levers to Deliver on our Ambitions until the Next Peak of the Cycle.

Growth



- Underlying PCT semi business
- New products and services
 - Synertia® platform
 - Pivoting IXS and IXM toward the semiconductor industry (e.g., CA20)
 - Dragonfly 3D World software
- Regional growth opportunities
- Non-semi growth (e.g. battery ...)

Ambition until the
next Peak of
the Cycle

670-770



445

Sales FY24 in
mn CHF

Efficiency & Resilience



- Full global footprint
- Operating leverage
- Cost efficiency
- Asian Hub in Penang
- Product line profitability

Ambition until the
next Peak of
the Cycle

22-27



13.6

EBITDA margin
FY24 in %

c•met